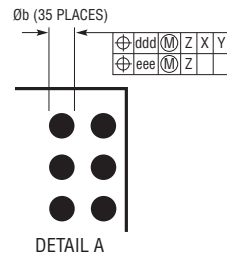
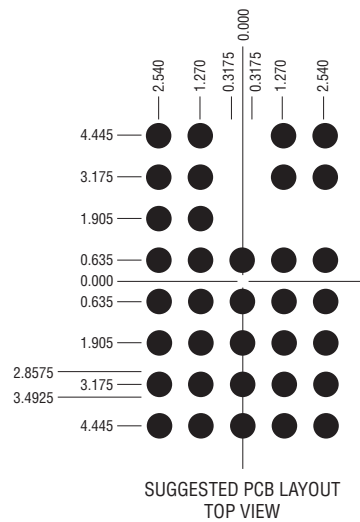
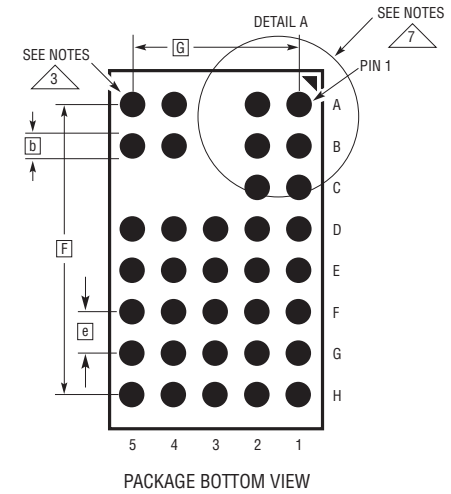
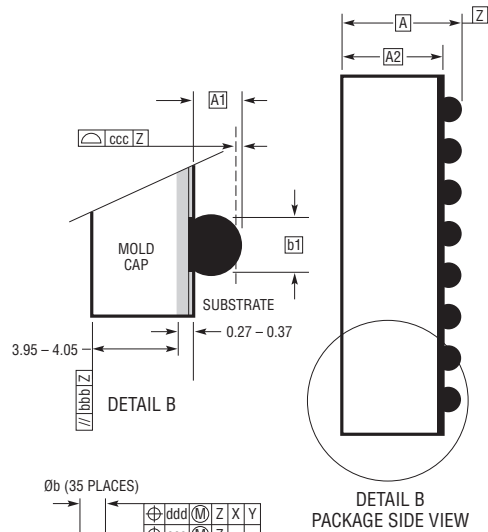
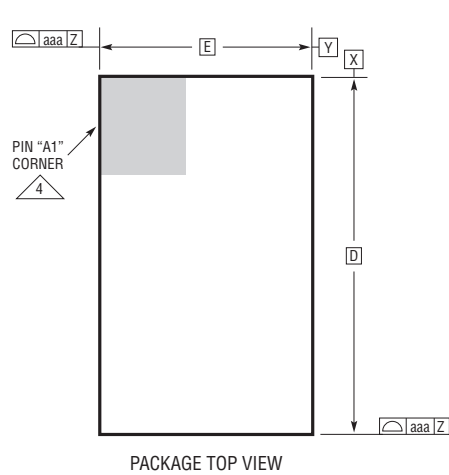


BGA Package
35-Lead (11.25mm × 6.25mm × 4.92mm)
 (Reference LTC DWG # 05-08-1879 Rev A)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.72	4.92	5.12	
A1	0.50	0.60	0.70	
A2	4.22	4.32	4.42	
b	0.71	0.78	0.85	
b1	0.60	0.63	0.66	
D		11.25		
E		6.25		
e		1.27		
F		8.89		
G		5.08		
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 35				

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
 - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 - 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

